Method and Apparatus for the Mounting of Semiconductor Chips

ABSTRACT

With the mounting of a semiconductor chip (1) onto a substrate (4) having a portion of adhesive (5) the bondhead (3) is lowered to a predetermined height H above a support (6) holding the substrate (4). At the same time, the pick-up tool (2) is fixed in an upper limit position on the bondhead (3). As soon as the bondhead (3) has reached the height H, the fixing of the pick-up tool (2) is released so that the pick-up tool (2) moves downwards from the upper limit position and presses the semiconductor chip (1) onto the adhesive (5). After a predetermined time after releasing the fixing of the pick-up tool (2), the bondhead (3) is raised and moved away.

With a bondhead (3) particularly suited for the method, the pick-up tool (2) and the bondhead (3) are connected by means of a chamber (12) to which compressed air and/or vacuum can be applied so that, to a large extent, the movement of the pick-up tool (2) can be controlled.

(Fig. 1)